

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPG20N04S4L-07	**Issued**	27. April 2022
MA#	MA005739607		
Package	PG-TDSON-8-4	**Weight***	97.60 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.592	1.63	1.63	16310	16310
chip_2	inorganic material	silicon	7440-21-3	1.592	1.63	1.63	16310	16310
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		137	
	non noble metal	iron	7439-89-6	0.044	0.05		456	
	non noble metal	copper	7440-50-8	44.409	45.50	45.56	455014	455607
wire	non noble metal	aluminium	7429-90-5	0.757	0.78	0.78	7761	7761
encapsulation	organic material	carbon black	1333-86-4	0.088	0.09		904	
	plastics	epoxy resin	-	6.263	6.42		64167	
	inorganic material	silicondioxide	60676-86-0	37.752	38.68	45.19	386808	451879
leadfinish	non noble metal	tin	7440-31-5	1.308	1.34	1.34	13398	13398
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	492	493
solder	non noble metal	tin	7440-31-5	0.070	0.07		715	
	noble metal	silver	7440-22-4	0.087	0.09		893	
	non noble metal	lead	7439-92-1	3.330	3.41	3.57	34121	35729
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.245	0.25	0.25	2509	2513
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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